DATA SHEET

PLATING
EPA, PACE

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Electrochemical deposition in an automatic system

Pure metal and alloy deposition as Au, Ag, Cu, Sn, Ni, SnAg for different applications in semiconductor, LED and microsystem technologies. Enhanced liquid flow and electrical field control ensure a homogenous deposition at highest plating rates. RENA offers customised solutions for special applications.

Areas of application

- Current redistribution layers for opto- and microelectronics
- Solder, Cu and Au bumps for wafer level packaging (WLP)
- Functional metallic layers for Micro - Electro - Mechanical Systems (MEMS)
- Micro forming and moulding for microsystems
- LED

Features and benefits

- Scalable throughput
- Wide layer thickness range
- Modular design for maximum flexibility
- Edge exclusion 0 / ≤ 3 mm
- Convertible for 4", 6", 8", 12" or for special wafer geometries like rectangular substrates
- Excellent uniformity
- Additional process modules for pre-treatment, etching and drying available
- Customised solutions with various plating chemicals
- Single and stacked layer processes
- > 15 years experience in plating tools

Cup plater

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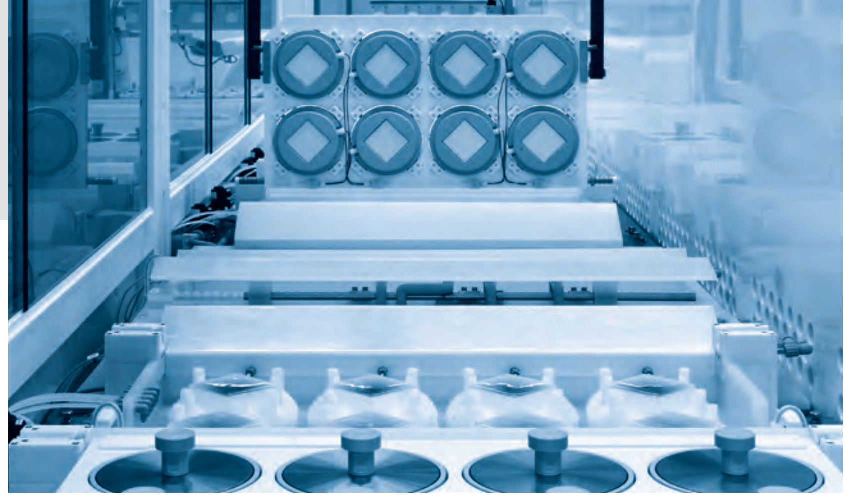
Wafer loading



Modular design

Technical Data EPA, PACE

Process	• Automatical loading • Pre-treatment / rinsing • Electroplating • Rinsing / etching • Drying • Automatical unloading
Dimensions	Depending on configuration
Throughput	Depending on configuration and process
Wafer	• 4 - 12“ • Round, square, customised
Edge exclusion	• EPA < 3 mm • PACE zero

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